Serial Number: 09/782,498 Filing Date: February 13, 2001

SMALL GRAIN SIZE, CONFORMAL ALUMINUM INTERCONNECTS AND METHOD FOR THEIR FORMATION

Claims 17-52 are now pending in this application. The Examiner is invited to contact the below-signed attorney with any questions regarding the present application.

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JUN 0 6 2001
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Respectfully submitted,

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By their Representatives,

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, Washington, D.C. 20231, on this \_\_\_\_\_ day of June, 2001.

Name

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